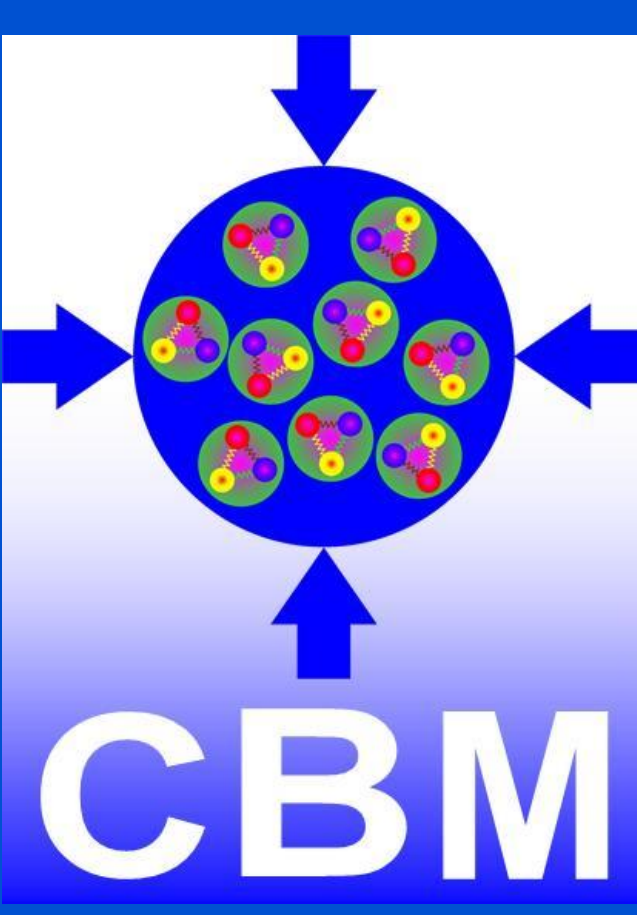
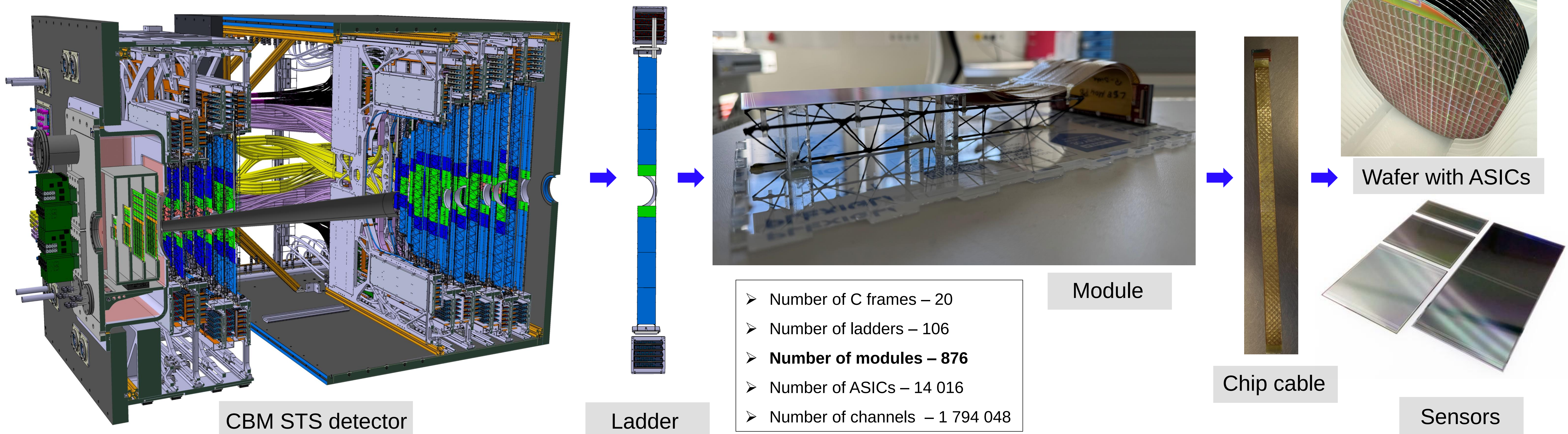


Successes to rework CBM-STS detector ladders and modules

GSI, for the MT annual meeting

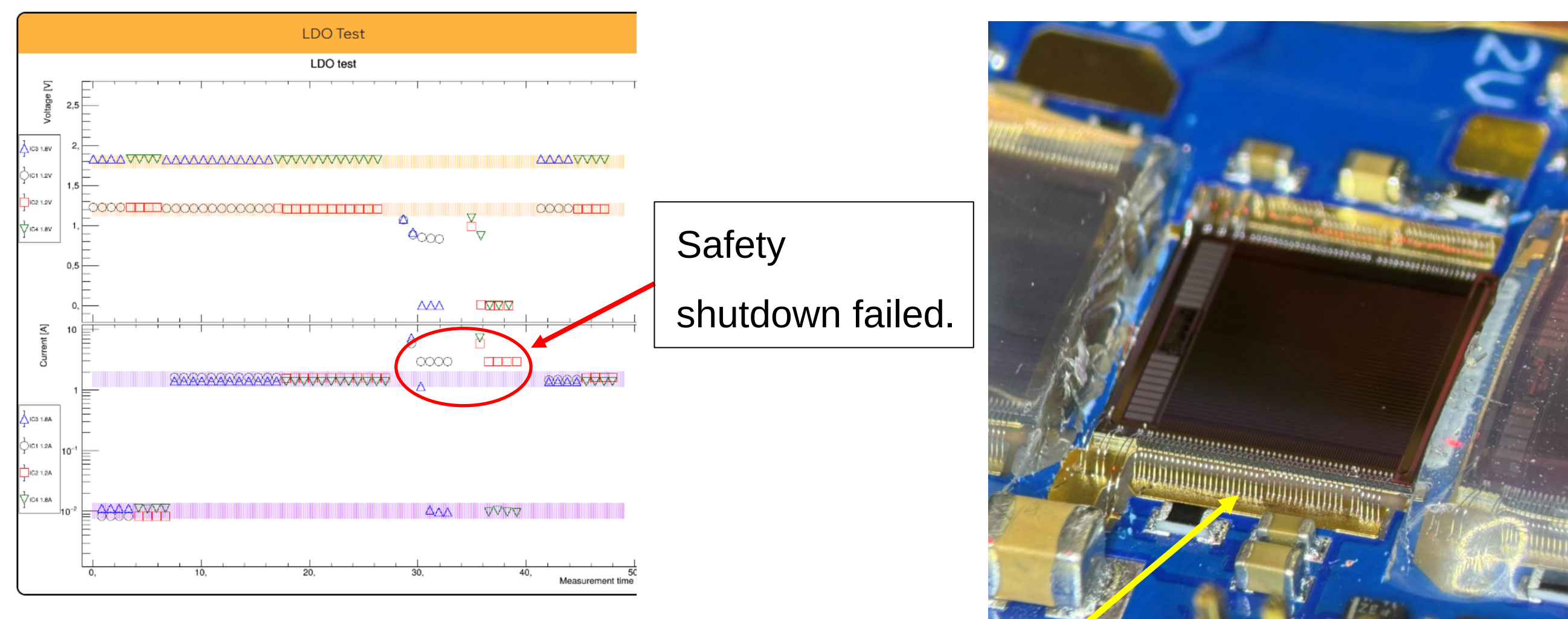


General view of the CBM detector and components



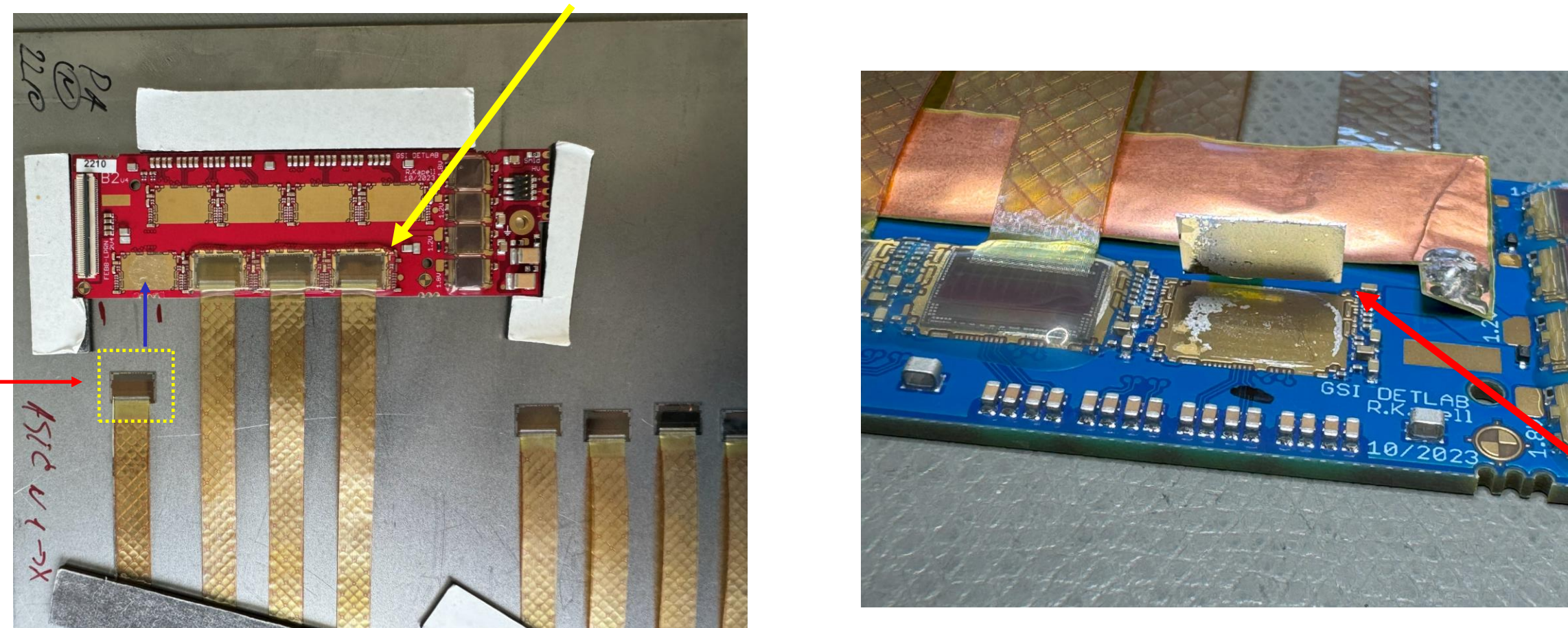
The assembly and repair process at each stage of module production

Removal of LDO

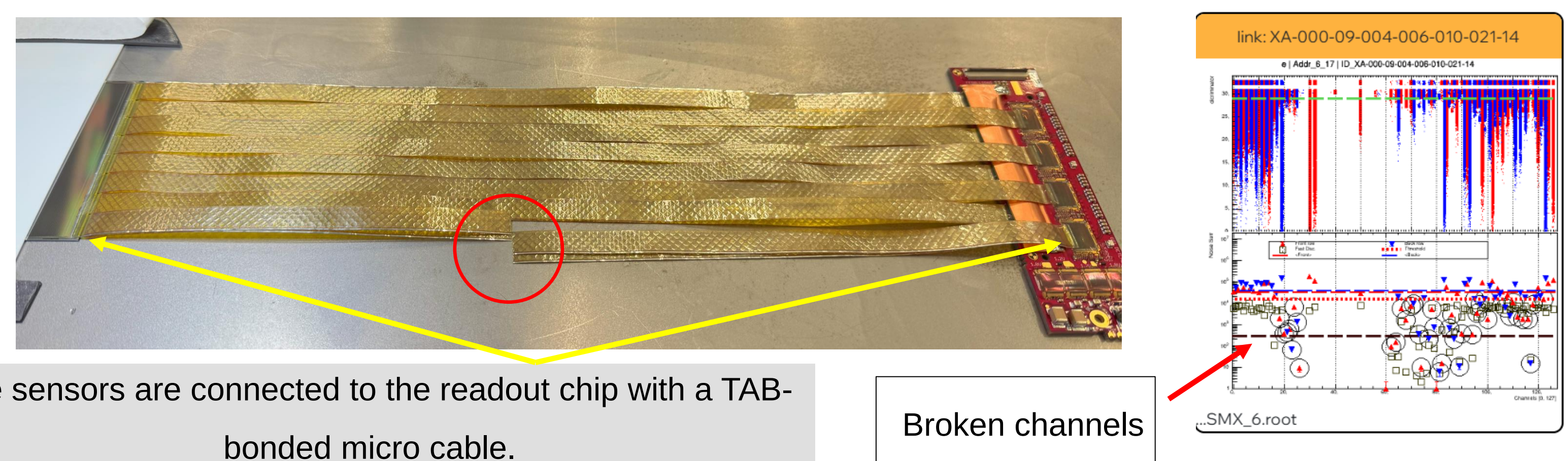


The LDO and readout chips are wire-bonded on the PCB.

The spare chip cable must be installed in a clean pad, replacing the damaged one

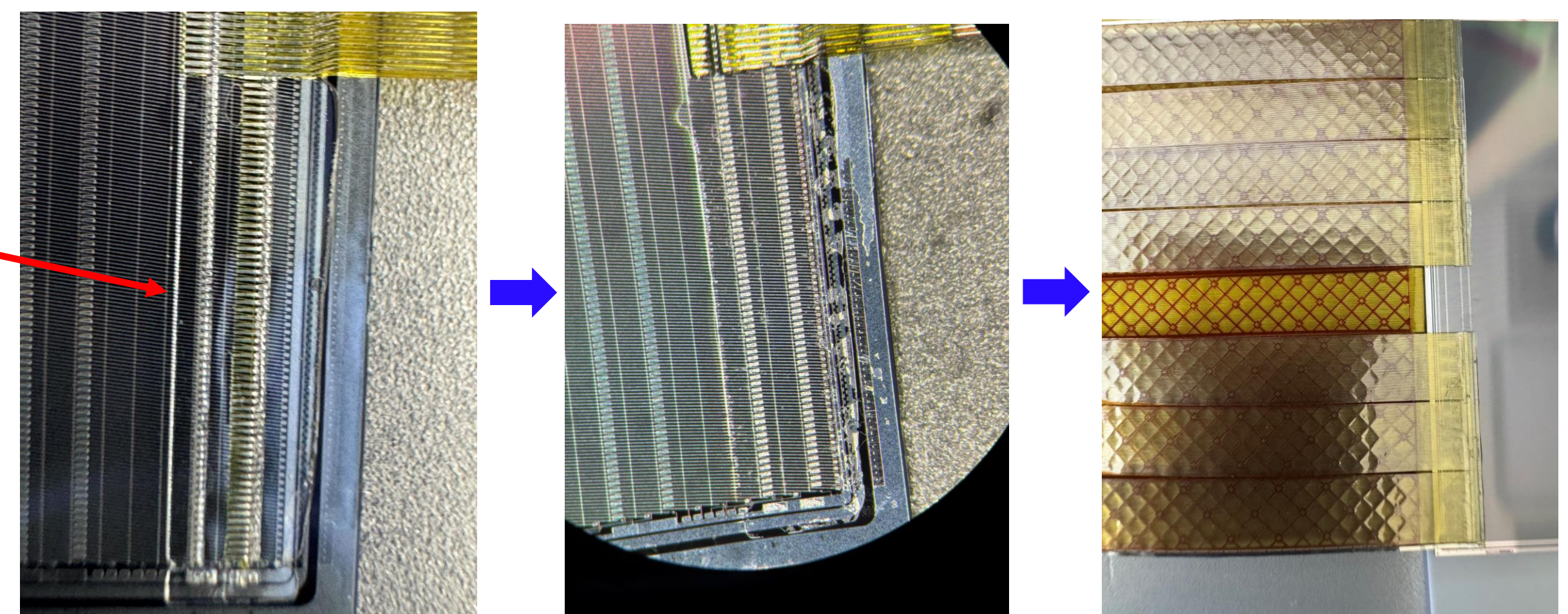


Removal of chip cable with multiple damaged channels

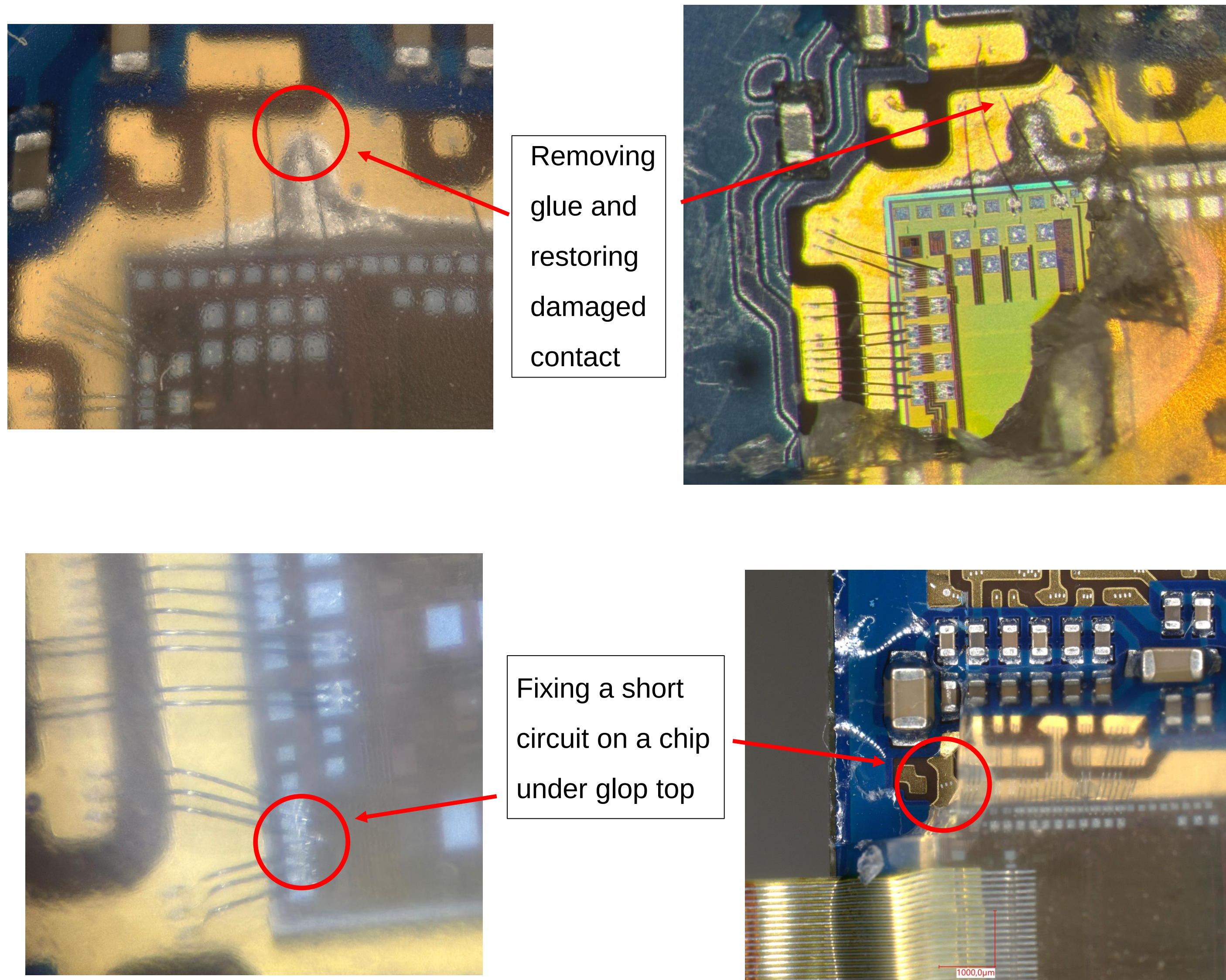


Removing the chip cable from the sensor surface and removing glue residue

Removing the damaged readout ASIC.



Repairing damaged connections under the glob top.



Removing the damaged module from the ladder and scraping the glue off the sensor surface

